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**Date:** 18 Jan 2011

**Product Category:** 16-bit Microcontrollers and Digital Signal Controllers; Analog (Linear & Mixed Signal) AND Interface; RF and Security; Touch Sensing Technologies; 8-bit Microcontrollers; All 16-bit Microcontrollers

**Device Family:**  

**Notification subject:** CCB# 946 Qualification of different paddle sizes in 18L & 28L SOIC packages at MMS (ATES).

**Notification text:** PCN Status:  
Final notification

Note: The 28L SOIC package qualification was completed and the PCN issued with attached qualification report on 6/28/2010. This notification includes the qualification report for the 18L SOIC package qualification.

Microchip Part#s Affected:  
See attachments of Affected Part Numbers Labeled as...  
PCN# CYER-01DNRB151\_Affected\_CPN.xls  
PCN# CYER-01DNRB151\_Affected\_CPN.pdf

Description of Change:  
Qualification of an different paddle size in 18L & 28L SOIC packages at MMS (ATES).

Pre Change:  
18L SOIC: 160 x 200 mils paddle  
28L SOIC: 160 x 205 mils paddle

Post Change:  
18L SOIC: 140 x 170 mils paddle  
28L SOIC: 200 x 240 mils paddle

Impacts to Data Sheet:  
None

Reason for Change:  
To improve manufacturability

Change Implementation Status:  
In Progress

Estimated First Ship Date:

28L SOIC: October 31, 2010 (Date code 1044) – see PCN revision history below

18L SOIC: February 28, 2011 (Date code 1110)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts, due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

PCN CYER-01DNRB151 Revision History:

April 1, 2010: Initial notification issued

June 28, 2010: Intermediate notification issued, which includes an attached qualification report and estimated first ship date of 10/31/2010 for the 28L SOIC package.

January 18, 2011: Final notification issued, which includes all of the above information and the addition of an attached qualification report and estimated first ship date of 2/28/2011 for the 18L SOIC package.

**Attachment(s):**

[PCN\\_CYER-01DNRB151\\_Affected\\_CPN.pdf](#) [PCN\\_CYER-01DNRB151\\_Affected\\_CPN.xls](#) [PCN\\_CYER-01DNRB151\\_Qual\\_Report\\_18L.pdf](#) [PCN\\_CYER-01DNRB151\\_Qual\\_Report\\_28L.pdf](#)

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**Product Change Notification - CYER-01DNRB151** [\(Printer Friendly\)](#)

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